| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 30307 | (coordinate or position or x-y ) same pad same (wir$3 or bond$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/07 11:32 |
| L2 | 1659 | (coordinate or position or x-y ) same pad same (wir$3 or bond$3)same tool | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/07 11:33 |
| L3 | 109 | 2 and pad with height | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/07 11:34 |
| L4 | 11 | 2 and pad with dummy | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/07 11:34 |
| S1 | 2 | "20050067678".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/04 17:26 |
| S2 | 1980 | (438/14).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 13:47 |
| S3 | 782 | (438/15).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 13:47 |
| S4 | 2493 | S2 S3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:47 |
| S5 | 1 | S4 and learn$3 near touch$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:14 |

| S8 | 4 | S4 and determin$3 near3 pad near4 (position$3 coordinate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:01 |
|----|---|---|---|----|----|---|
| S9 | 0 | S4 and dummy with pad near4 (position$3 coordinate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:51 |
| S10 | 174 | S4 and pad near4 (position$3 coordinate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:52 |
| S11 | 1294 | wire near2 bond$3 with pad near4 (position$3 coordinate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:52 |
| S12 | 5 | S11 and S4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:54 |
| S13 | 29 | (wire with bonding with operation).clm. and "438"/$.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:56 |
| S14 | 250 | wafer with bonding with tool | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:57 |
| S15 | 144 | S14 and pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 13:57 |
| S16 | 40 | S15 and sensing | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:01 |

| S17 | 2597 | (438/612).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 14:46 |
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| S18 | 419 | (438/617).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 14:01 |
| S19 | 94 | S18 and pad near4 (position$3 coordinate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:06 |
| S20 | 44 | S18 and pad near4 (position$3 coordinate) | USPAT | OR | ON | 2005/11/05 14:01 |
| S21 | 2902 | S18 S17 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:06 |
| S22 | 25 | S21 and dummy with pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:06 |
| S23 | 17 | S21 and dummy with pad | USPAT | OR | ON | 2005/11/05 14:07 |
| S24 | 51 | S21 and (dummy with pad anchors) | USPAT | OR | ON | 2005/11/05 14:07 |
| S25 | 8 | ("5700735"\| "5734200"\| "5736791" \| "5773899"\| "5962919"\| "6002179").PN. OR ("6165886"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 14:12 |
| S26 | 97 | pad near4 height and S21 | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 14:13 |
| S27 | 66 | pad near4 height and S21 | USPAT | OR | ON | 2005/11/05 14:13 |
| S28 | 106 | learn$3 near touch$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:14 |
| S29 | 1 | learn$3 near touch$3 and wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:15 |

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| S30 | 23 | learn$3 near touch$3 and pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:16 |
| S31 | 131 | bonding with tool and S21 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:17 |
| S32 | 89 | bonding with tool and S21 | USPAT | OR | ON | 2005/11/05 14:21 |
| S33 | 74 | S31 and wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:17 |
| S34 | 68 | S33 and wir$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:17 |
| S35 | 44 | S33 and wir$3 | USPAT | OR | ON | 2005/11/05 14:17 |
| S36 | 5 | bonding with tool same dummy near3 pad | USPAT | OR | ON | 2005/11/05 14:25 |
| S37 | 2 | bonding with tool same dummy near3 pad | US-PGPUB | OR | ON | 2005/11/05 14:26 |
| S38 | 5 | bonding with tool same dummy near3 pad | USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:29 |
| S39 | 1 | 1989-321630.NRAN. | DERWENT | OR | ON | 2005/11/05 14:28 |
| S40 | 10 | bonding and tool and dummy and pad | USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:32 |
| S41 | 17 | height with pad with sensing | USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:34 |
| S42 | 10 | height with pad with sensing | US-PGPUB | OR | ON | 2005/11/05 14:35 |
| S43 | 27 | height with pad with sensing | USPAT | OR | ON | 2005/11/05 14:35 |
| S44 | 94 | height with pad with tool | USPAT | OR | ON | 2005/11/05 14:35 |
| S45 | 36 | height near5 pad with tool | USPAT | OR | ON | 2005/11/05 14:38 |
| S46 | 0 | pad with coodinate | USPAT | OR | ON | 2005/11/05 14:38 |
| S47 | 1003 | pad with coordinate | USPAT | OR | ON | 2005/11/05 14:38 |
| S48 | 36 | pad near2 coordinate and wafer and tool | USPAT | OR | ON | 2005/11/05 14:39 |
| S49 | 557 | reference near3 pad and tool | USPAT | OR | ON | 2005/11/05 14:39 |

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| S50 | 42 | reference near3 pad and tool and "438"/$.ccls. | USPAT | OR | ON | 2005/11/05 14:41 |
| S51 | 5 | bonding with tool same dummy with pad | USPAT | OR | ON | 2005/11/05 14:41 |
| S52 | 2 | pad with coordinate and dummy adj pad | USPAT | OR | ON | 2005/11/05 14:43 |
| S53 | 33 | pad with height same bonding with tool | USPAT | OR | ON | 2005/11/05 14:44 |
| S54 | 11400 | pad near2 position | USPAT | OR | ON | 2005/11/05 14:45 |
| S55 | 131 | S54 and bonding near3 tool | USPAT | OR | ON | 2005/11/05 14:45 |
| S56 | 23 | S55 and pad with height | USPAT | OR | ON | 2005/11/05 14:45 |
| S57 | 257 | S17 and pad with (coordinate positon location) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:49 |
| S58 | 160 | S57 and wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:47 |
| S59 | 168 | S57 and wir$4 near2 bond$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:47 |
| S60 | 65 | S18 and pad with (coordinate positon location) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:53 |
| S61 | 3042 | (Wire with bonding with method).ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:54 |
| S62 | 3 | S61 and (dummy with pad).ab. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 14:54 |
| S63 | 2 | S61 and (dummy with pad).clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:23 |

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| S64 | 7 | S61 and (dummy with pad) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:24 |
| S65 | 0 | determine with positon with pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:24 |
| S66 | 937 | determine with position with pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:24 |
| S68 | 13 | S66 and bonding with tool | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:28 |
| S69 | 10 | S66 and wire with tool | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:28 |
| S70 | 77 | ("4342090" | "4674670" | "4765531" | "5052606" | "5082165" | "5108023").PN. OR ("5307978"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:29 |
| S71 | 1111 | pad with (pressure stress) with tool | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:30 |
| S72 | 5 | S18 and pad with (pressure stress) with tool | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:31 |
| S73 | 5 | S18 and pad with (pressure stress shock) with tool | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:32 |
| S74 | 9 | S17 and pad with (pressure stress shock) with tool | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:32 |
| S75 | 88 | "438"/$.ccls. and pad with (pressure stress shock) with tool | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:38 |
| S76 | 80 | (438/120).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 15:37 |

| S77 | 3224 | (438/106).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/05 15:38 |
|------|------|------|------|------|------|------|
| S78 | 209 | S77 and pad with (pressure stress shock) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/05 15:38 |
| S79 | 218 | S77 and pad with (pressure stress shock) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/05 15:38 |
| S80 | 131 | S79 and (wire wiring) with (bond bonding) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/07 11:25 |